KL Pey's contributions to journals and conferences

Editor/Reviewer/Technical Committee Member

- ***Editor***, IEEE Transaction on Device and Materials Reliability (TDMR), August 2009 – present.
- ***Past chair***, Neuromorphic Computing Committee, 2022 IEEE International Reliability Physics Symposium (IRPS), USA.
- ***Technical committee member***, Neuromorphic Computing Committee, 2023 IEEE International Reliability Physics Symposium (IRPS), USA.
- ***Technical program committee member***, IEEE International Symposium on VLSI Technology, Systems and Applications (VLSI-TSA), 2014 – 2023, Taiwan.
- ***Chair***, Neuromorphic Computing Committee, 2021 IEEE International Reliability Physics Symposium (IRPS), USA.
- ***Co-chair and moderator***, 2021 IEEE IRPS Neuromorphic Device Reliability Workshop, USA.
- ***Dy-Chair***, Neuromorphic Computing Committee, 2020 IEEE International Reliability Physics Symposium (IRPS), USA.
- ***Co-chair and moderator***, 2020 IEEE IRPS Neuromorphic Device Reliability Workshop, 29th March – 2nd April 2020, Dallas, Texas, USA.
- ***Co-chair and moderator***, 2019 IEEE IRPS Neuromorphic Device Reliability Workshop, 31st March – 4th April 2019, Monterey, USA.
- ***Technical committee member***, Neuromorphic Computing Committee (new committee), 2019 IEEE International Reliability Physics Symposium (IRPS), USA.
- ***Technical program committee*** for Reliability, IEEE Electron Devices Technology and Manufacturing (EDTM), 2017 – 2019, Asia.
- ***Editorial***, IEEE-TDMR Special Issue from IRSP Stress Workshop 2018.
- ***Technical committee member***, Conventional gate dielectrics Committee, 2006, 2007, 2008, 2010, 2011, 2013-2015 and 2019 IEEE International Reliability Physics Symposium (IRPS), USA.
- ***Technical program committee***, 20th Insulating Films on Semiconductors (INFOS 2017) Conference, June 27th - 30th, 2017.
- ***Technical program committee***, 19th Insulating Films on Semiconductors (INFOS 2015) Conference, 29th June – 2nd July 2015.
- ***Technical sub-committee member***, CMOS & Interconnect Reliability (CIR) Sub-committee, 2007 and 2008 IEEE International Electron Device Meeting (IEDM), USA.
- ***Co-chair***, Gate Dielectrics Committee, 2013 IEEE International Reliability Physics Symposium (IRPS), USA.
- ***Technical program committee member*****,** 2010 International Conference on Solid State and Integrated Circuit Technology (ICSICT'2010), Shanghai, China.
- ***Technical program committee member*****,** 2008 International Conference on Solid State and Integrated Circuit Technology (ICSICT'2008), Beijing, China.
- ***Co-chair***, Novel Gate Stack/Dielectrics and FEOL Reliability and Failure Mechanisms Committee, 2010 IEEE 17th Physical and Failure Analysis of Integrated Circuits (IPFA), Singapore.

- ***Chair***, Novel Gate Stack/Dielectrics and FEOL Reliability Committee, 2009 IEEE 16th Physical and Failure Analysis of Integrated Circuits (IPFA), Suzhou, China.
- ***Co-chair***, Novel Gate Stack/Dielectrics and FEOL Reliability and Failure Mechanisms Committee, 2008 IEEE 15th Physical and Failure Analysis of Integrated Circuits (IPFA), Singapore.
- ***Guest Editor***, 2003, 2004, 2005 and 2007 of IEEE Transactions on Device and Materials Reliability.
- ***Reviewer*** of international refereed journals - IEEE Electron Device Letters, IEEE Transactions on electron Device, IEEE Transactions on Device and Materials Reliability, Electrochemical and Solid-state Letters, Journal of Electrochemical Society, Solid-State Electronics, Thin Solid Films, European Journal of Applied Physics and Applied Physics Letters.
- ***Reviewer*** of 2006 A*STAR Temasek Research Program.
- ***Co-chair***, Frontend Reliability Committee, 2007 IEEE 14th Physical and Failure Analysis of Integrated Circuits (IPFA), India.
- ***Co-chair***, Novel Device Architectures Committee, Design, Processes, and Characterization, 2006 IEEE 13th Physical and Failure Analysis of Integrated Circuits (IPFA), Singapore.
- ***Chair***, IC Failure Analysis Committee, 2004 IEEE 11th Physical and Failure Analysis of Integrated Circuits (IPFA), Taiwan.
- ***Technical committee member***, Advanced Interconnects Reliability Committee, 2003 IEEE 10th Physical and Failure Analysis of Integrated Circuits (IPFA), Singapore.
- ***Chair***, Advanced Interconnects Reliability Committee, 2002 IEEE 9th Physical and Failure Analysis of Integrated Circuits (IPFA), Singapore.